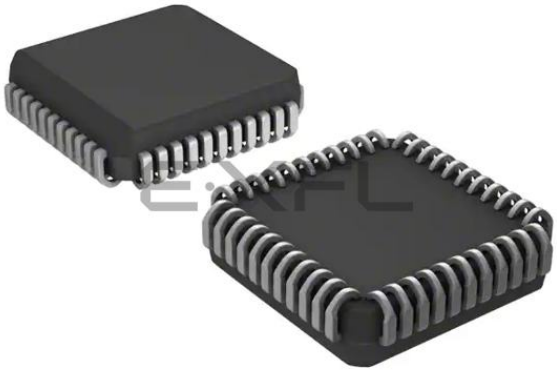

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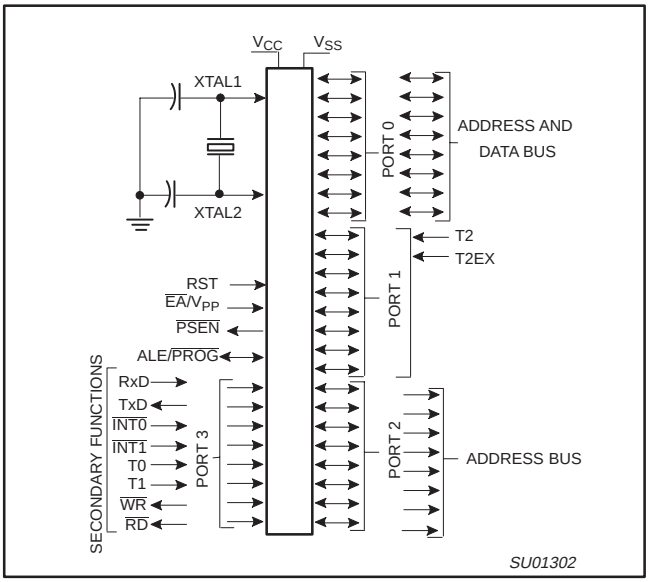
Applications of "Embedded - Microcontrollers"

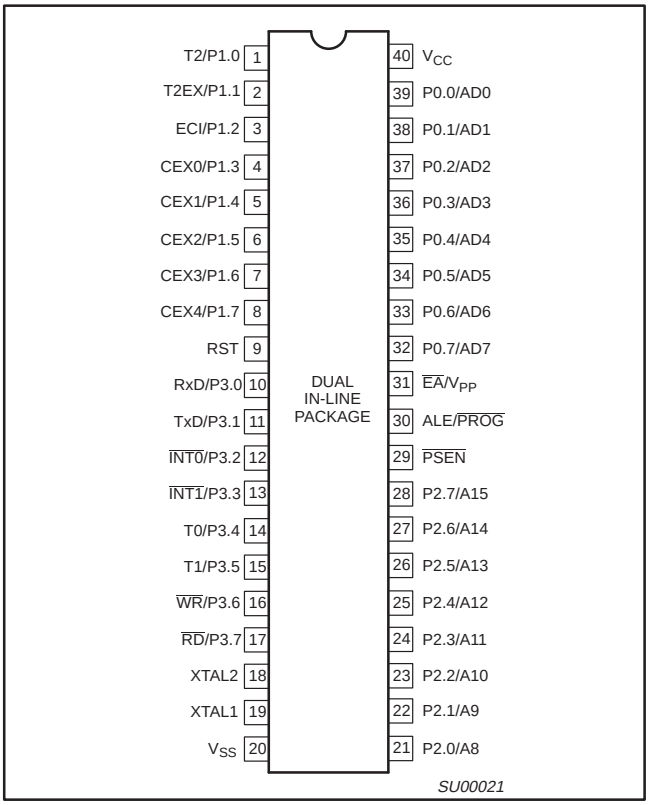
Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89c51rc2ba-01-512

LOGIC SYMBOL

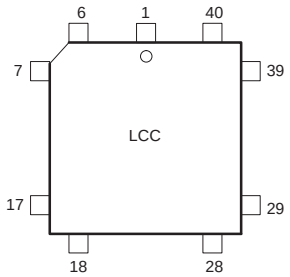


PINNING

Plastic Dual In-Line Package



Plastic Leaded Chip Carrier

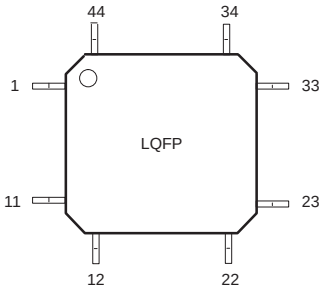


Pin	Function	Pin	Function	Pin	Function
1	NIC*	16	P3.4/T0	31	P2.7/A15
2	P1.0/T2	17	P3.5/T1	32	PSEN
3	P1.1/T2EX	18	P3.6/WR	33	ALE/PROG
4	P1.2/ECI	19	P3.7/RD	34	NIC*
5	P1.3/CEX0	20	XTAL2	35	EA/VPP
6	P1.4/CEX1	21	XTAL1	36	P0.7/AD7
7	P1.5/CEX2	22	VSS	37	P0.6/AD6
8	P1.6/CEX3	23	NIC*	38	P0.5/AD5
9	P1.7/CEX4	24	P2.0/A8	39	P0.4/AD4
10	RST	25	P2.1/A9	40	P0.3/AD3
11	P3.0/RxD	26	P2.2/A10	41	P0.2/AD2
12	NIC*	27	P2.3/A11	42	P0.1/AD1
13	P3.1/TxD	28	P2.4/A12	43	P0.0/AD0
14	P3.2/INT0	29	P2.5/A13	44	VCC
15	P3.3/INT1	30	P2.6/A14		

* NO INTERNAL CONNECTION

SU00023

Plastic Quad Flat Pack



Pin	Function	Pin	Function	Pin	Function
1	P1.5/CEX2	16	VSS	31	P0.6/AD6
2	P1.6/CEX3	17	NIC*	32	P0.5/AD5
3	P1.7/CEX4	18	P2.0/A8	33	P0.4/AD4
4	RST	19	P2.1/A9	34	P0.3/AD3
5	P3.0/RxD	20	P2.2/A10	35	P0.2/AD2
6	NIC*	21	P2.3/A11	36	P0.1/AD1
7	P3.1/TxD	22	P2.4/A12	37	P0.0/AD0
8	P3.2/INT0	23	P2.5/A13	38	VCC
9	P3.3/INT1	24	P2.6/A14	39	NIC*
10	P3.4/T0	25	P2.7/A15	40	P1.0/T2
11	P3.5/T1	26	PSEN	41	P1.1/T2EX
12	P3.6/WR	27	ALE/PROG	42	P1.2/ECI
13	P3.7/RD	28	NIC*	43	P1.3/CEX0
14	XTAL2	29	EA/VPP	44	P1.4/CEX1
15	XTAL1	30	P0.7/AD7		

* NO INTERNAL CONNECTION

SU01400

PIN DESCRIPTIONS

MNEMONIC	PIN NUMBER			TYPE	NAME AND FUNCTION
	PDIP	PLCC	LQFP		
V_{SS}	20	22	16	I	**Ground:** 0 V reference.
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle, and power-down operation.
P0.0–0.7	39–32	43–36	37–30	I/O	**Port 0:** Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high-impedance inputs. Port 0 is also the multiplexed low-order address and data bus during accesses to external program and data memory. In this application, it uses strong internal pull-ups when emitting 1s.
P1.0–P1.7	1–8	2–9	40–44, 1–3	I/O	**Port 1:** Port 1 is an 8-bit bidirectional I/O port with internal pull-ups on all pins. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 1 pins that are externally pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}).
					Alternate functions for P89C51RA2/RB2/RC2/RD2xx Port 1 include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout (see Programmable Clock-Out)
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
	3	4	42	I	**ECI (P1.2):** External Clock Input to the PCA
	4	5	43	I/O	**CEX0 (P1.3):** Capture/Compare External I/O for PCA module 0
	5	6	44	I/O	**CEX1 (P1.4):** Capture/Compare External I/O for PCA module 1
	6	7	1	I/O	**CEX2 (P1.5):** Capture/Compare External I/O for PCA module 2
	7	8	2	I/O	**CEX3 (P1.6):** Capture/Compare External I/O for PCA module 3
	8	9	3	I/O	**CEX4 (P1.7):** Capture/Compare External I/O for PCA module 4
P2.0–P2.7	21–28	24–31	18–25	I/O	**Port 2:** Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 2 pins that are externally being pulled low will source current because of the internal pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR). In this application, it uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOV @Ri), port 2 emits the contents of the P2 special function register.
P3.0–P3.7	10–17	11, 13–19	5, 7–13	I/O	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, port 3 pins that are externally being pulled low will source current because of the pull-ups. (See DC Electrical Characteristics: I_{IL}). Port 3 also serves the special features of the P89C51RA2/RB2/RC2/RD2xx, as listed below:
	10	11	5	I	**RxD (P3.0):** Serial input port
	11	13	7	O	**TxD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt
	13	15	9	I	**$\overline{\text{INT1}}$ (P3.3):** External interrupt
	14	16	10	I	**T0 (P3.4):** Timer 0 external input
	15	17	11	I	**T1 (P3.5):** Timer 1 external input
	16	18	12	O	**$\overline{\text{WR}}$ (P3.6):** External data memory write strobe
	17	19	13	O	**$\overline{\text{RD}}$ (P3.7):** External data memory read strobe
RST	9	10	4	I	**Reset:** A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal resistor to V_{SS} permits a power-on reset using only an external capacitor to V_{CC}.
ALE	30	33	27	O	**Address Latch Enable:** Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted twice every machine cycle, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. ALE can be disabled by setting SFR auxiliary.0. With this bit set, ALE will be active only during a MOVX instruction.

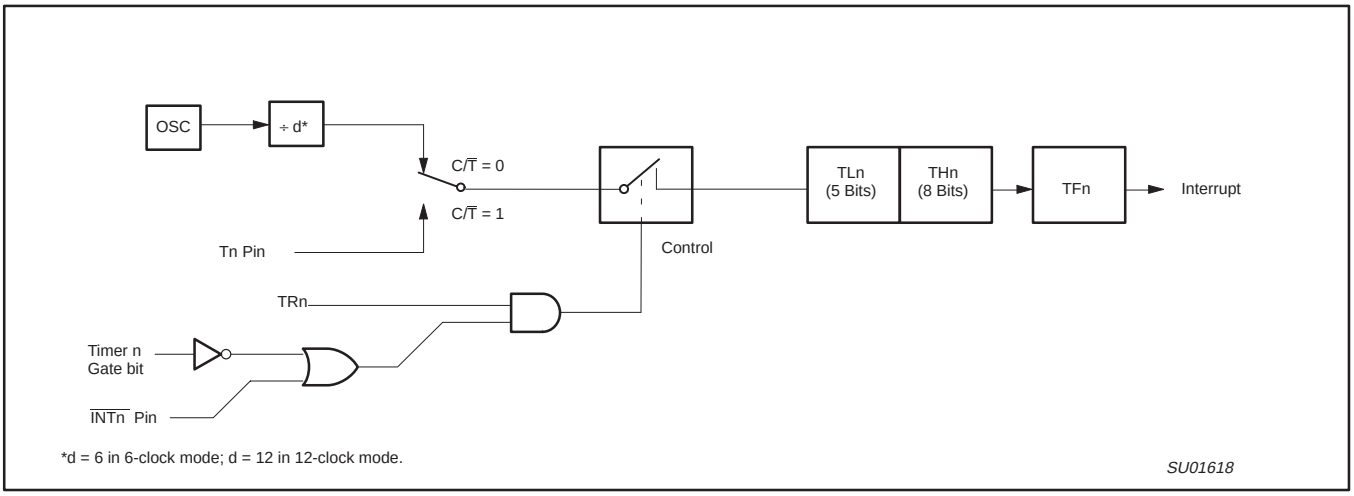


Figure 2. Timer/Counter 0/1 Mode 0: 13-Bit Timer/Counter

TCON Address = 88H Reset Value = 00H

Bit Addressable

7	6	5	4	3	2	1	0
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0

BIT	SYMBOL	FUNCTION
TCON.7	TF1	Timer 1 overflow flag. Set by hardware on Timer/Counter overflow. Cleared by hardware when processor vectors to interrupt routine, or clearing the bit in software.
TCON.6	TR1	Timer 1 Run control bit. Set/cleared by software to turn Timer/Counter on/off.
TCON.5	TF0	Timer 0 overflow flag. Set by hardware on Timer/Counter overflow. Cleared by hardware when processor vectors to interrupt routine, or by clearing the bit in software.
TCON.4	TR0	Timer 0 Run control bit. Set/cleared by software to turn Timer/Counter on/off.
TCON.3	IE1	Interrupt 1 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TCON.2	IT1	Interrupt 1 type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.
TCON.1	IE0	Interrupt 0 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TCON.0	IT0	Interrupt 0 Type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.

SU01516

Figure 3. Timer/Counter 0/1 Control (TCON) Register

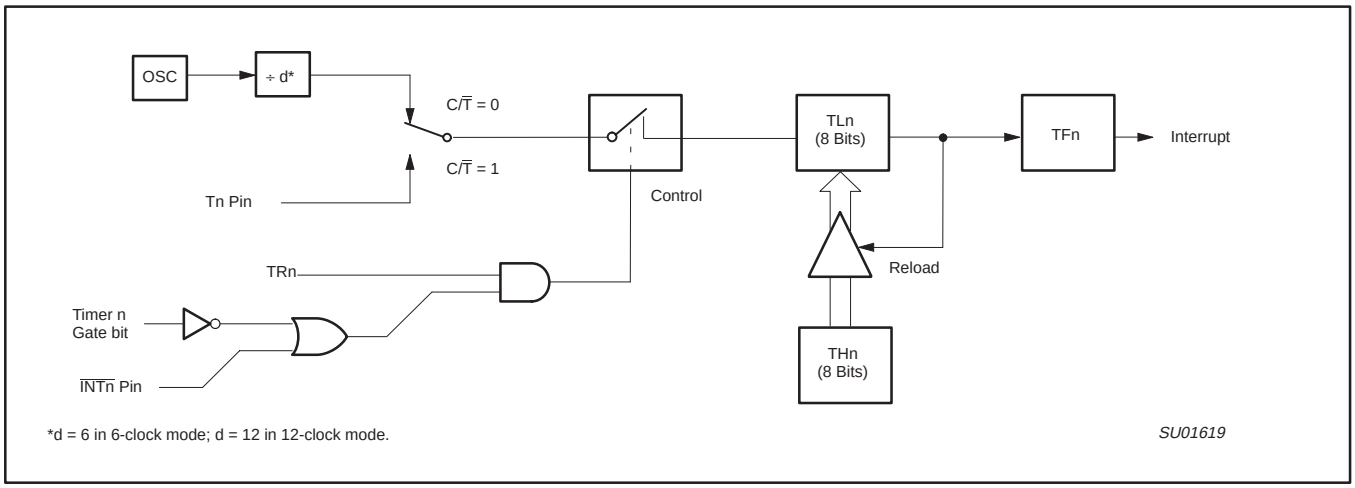


Figure 4. Timer/Counter 0/1 Mode 2: 8-Bit Auto-Reload

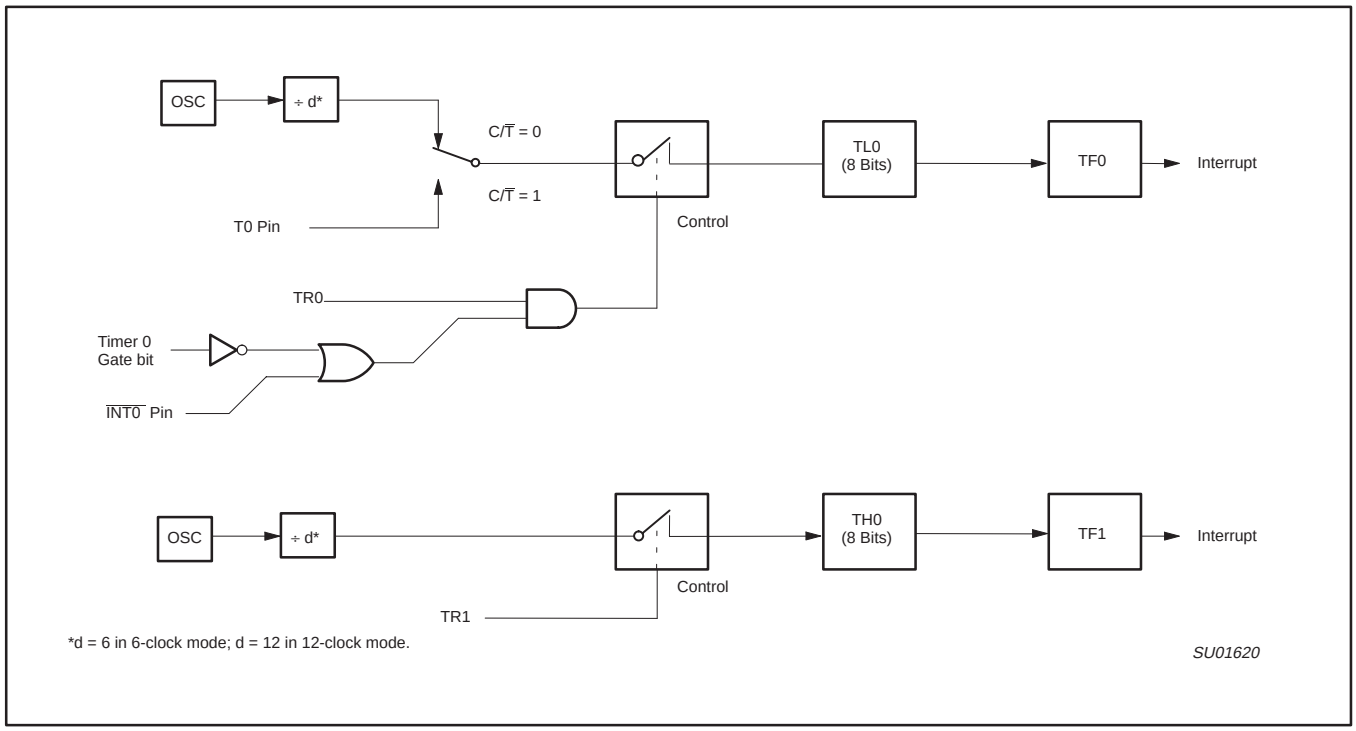
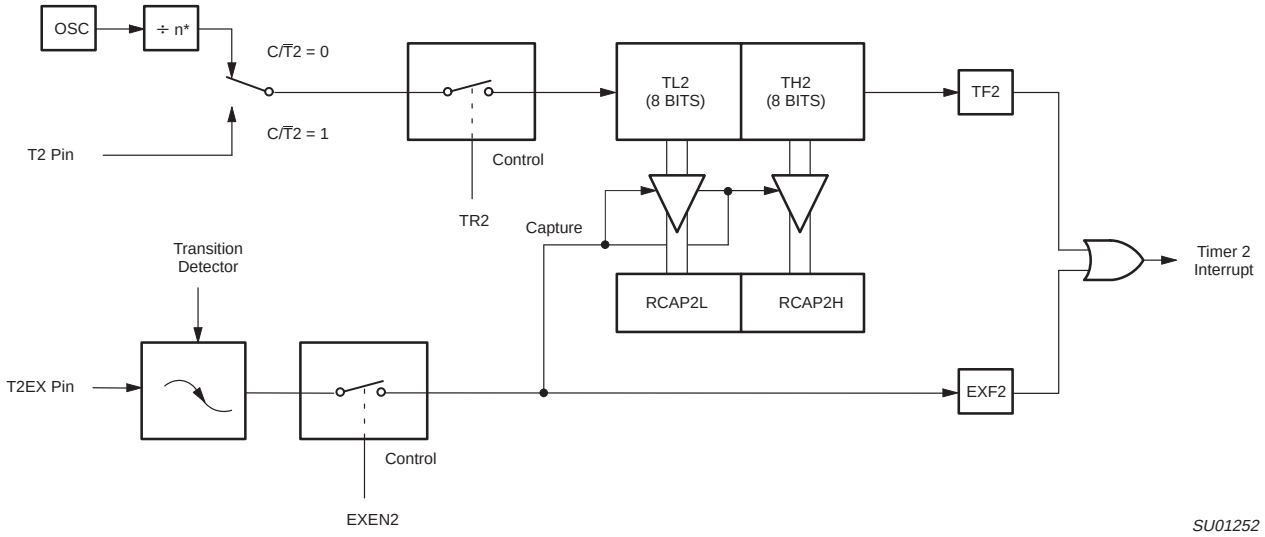


Figure 5. Timer/Counter 0 Mode 3: Two 8-Bit Counters

Table 3. Timer 2 Operating Modes

RCLK + TCLK	CP/$\overline{RL2}$	TR2	MODE
0	0	1	16-bit Auto-reload
0	1	1	16-bit Capture
1	X	1	Baud rate generator
X	X	0	(off)



* n = 6 in 6-clock mode, or 12 in 12-clock mode.

Figure 7. Timer 2 in Capture Mode

T2MOD Address = 0C9H Reset Value = XXXX XX00B

Not Bit Addressable

—	—	—	—	—	—	T2OE	DCEN
Bit 7	6	5	4	3	2	1	0

Symbol	Function
—	Not implemented, reserved for future use.*
T2OE	Timer 2 Output Enable bit.
DCEN	Down Count Enable bit. When set, this allows Timer 2 to be configured as an up/down counter.

* User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU00729

Figure 8. Timer 2 Mode (T2MOD) Control Register

SCON Address = 98H Reset Value = 00H

Bit Addressable

7	6	5	4	3	2	1	0
SM0	SM1	SM2	REN	TB8	RB8	TI	RI

Where SM0, SM1 specify the serial port mode, as follows:

SM0	SM1	Mode	Description	Baud Rate
0	0	0	shift register	$f_{OSC}/12$ (12-clock mode) or $f_{OSC}/6$ (6-clock mode)
0	1	1	8-bit UART	variable
1	0	2	9-bit UART	$f_{OSC}/64$ or $f_{OSC}/32$ (12-clock mode) or $f_{OSC}/32$ or $f_{OSC}/16$ (6-clock mode)
1	1	3	9-bit UART	variable

SM2 Enables the multiprocessor communication feature in Modes 2 and 3. In Mode 2 or 3, if SM2 is set to 1, then RI will not be activated if the received 9th data bit (RB8) is 0. In Mode 1, if SM2=1 then RI will not be activated if a valid stop bit was not received. In Mode 0, SM2 should be 0.

REN Enables serial reception. Set by software to enable reception. Clear by software to disable reception.

TB8 The 9th data bit that will be transmitted in Modes 2 and 3. Set or clear by software as desired.

RB8 In Modes 2 and 3, is the 9th data bit that was received. In Mode 1, it SM2=0, RB8 is the stop bit that was received. In Mode 0, RB8 is not used.

TI Transmit interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission. Must be cleared by software.

RI Receive interrupt flag. Set by hardware at the end of the 8th bit time in Mode 0, or halfway through the stop bit time in the other modes, in any serial reception (except see SM2). Must be cleared by software.

SU01626

Figure 12. Serial Port Control (SCON) Register

Baud Rate			f_{OSC}	SMOD	Timer 1		
Mode	12-clock mode	6-clock mode			C/$\overline{T}$	Mode	Reload Value
Mode 0 Max	1.67 MHz	3.34 MHz	20 MHz	X	X	X	X
Mode 2 Max	625 k	1250 k	20 MHz	1	X	X	X
Mode 1, 3 Max	104.2 k	208.4 k	20 MHz	1	0	2	FFH
Mode 1, 3	19.2 k	38.4 k	11.059 MHz	1	0	2	FDH
	9.6 k	19.2 k	11.059 MHz	0	0	2	FDH
	4.8 k	9.6 k	11.059 MHz	0	0	2	FAH
	2.4 k	4.8 k	11.059 MHz	0	0	2	F4H
	1.2 k	2.4 k	11.059 MHz	0	0	2	E8H
	137.5	275	11.986 MHz	0	0	2	1DH
	110	220	6 MHz	0	0	2	72H
	110	220	12 MHz	0	0	1	FEEBH

Figure 13. Timer 1 Generated Commonly Used Baud Rates

More About Mode 0

Serial data enters and exits through RxD. TxD outputs the shift clock. 8 bits are transmitted/received: 8 data bits (LSB first). The baud rate is fixed a 1/12 the oscillator frequency (12-clock mode) or 1/6 the oscillator frequency (6-clock mode).

Figure 14 shows a simplified functional diagram of the serial port in Mode 0, and associated timing.

Transmission is initiated by any instruction that uses SBUF as a destination register. The “write to SBUF” signal at S6P2 also loads a 1 into the 9th position of the transmit shift register and tells the TX Control block to commence a transmission. The internal timing is such that one full machine cycle will elapse between “write to SBUF” and activation of SEND.

SEND enables the output of the shift register to the alternate output function line of P3.0 and also enable SHIFT CLOCK to the alternate output function line of P3.1. SHIFT CLOCK is low during S3, S4, and S5 of every machine cycle, and high during S6, S1, and S2. At S6P2 of every machine cycle in which SEND is active, the contents of the transmit shift are shifted to the right one position.

As data bits shift out to the right, zeros come in from the left. When the MSB of the data byte is at the output position of the shift register, then the 1 that was initially loaded into the 9th position, is just to the left of the MSB, and all positions to the left of that contain zeros. This condition flags the TX Control block to do one last shift and then deactivate SEND and set T1. Both of these actions occur at S1P1 of the 10th machine cycle after “write to SBUF.”

Reception is initiated by the condition REN = 1 and R1 = 0. At S6P2 of the next machine cycle, the RX Control unit writes the bits 11111110 to the receive shift register, and in the next clock phase activates RECEIVE.

RECEIVE enable SHIFT CLOCK to the alternate output function line of P3.1. SHIFT CLOCK makes transitions at S3P1 and S6P1 of every machine cycle. At S6P2 of every machine cycle in which RECEIVE is active, the contents of the receive shift register are

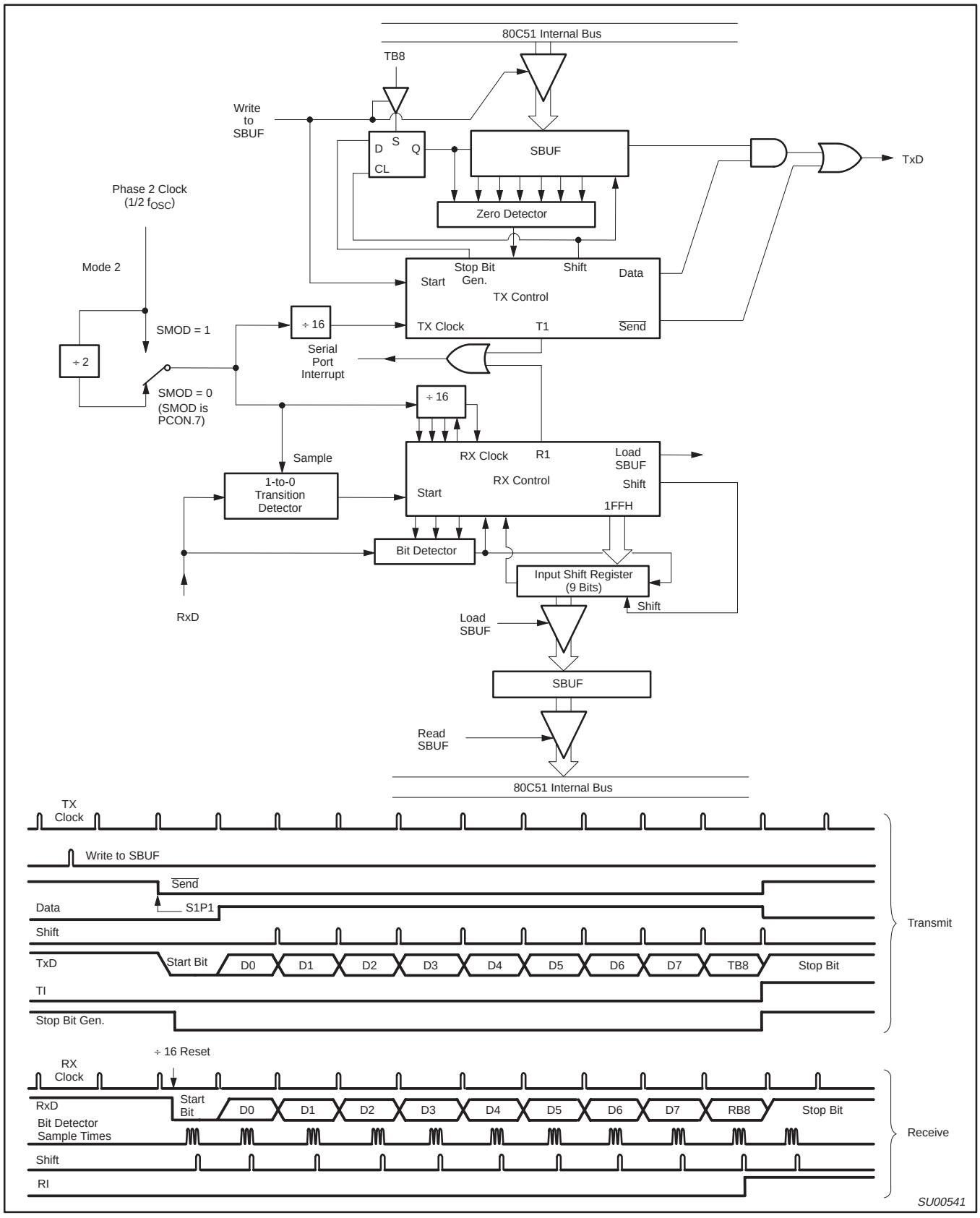


Figure 16. Serial Port Mode 2

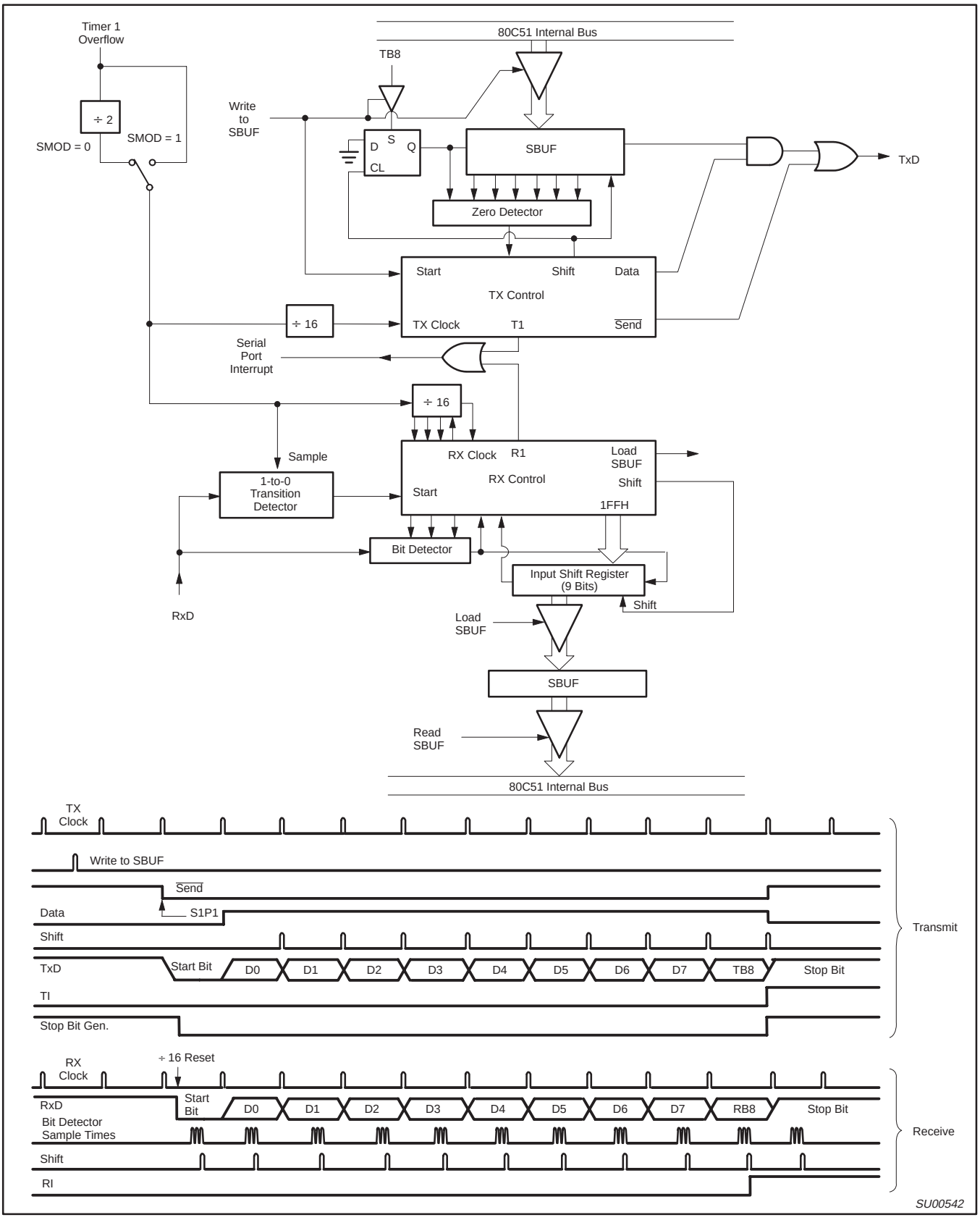


Figure 17. Serial Port Mode 3

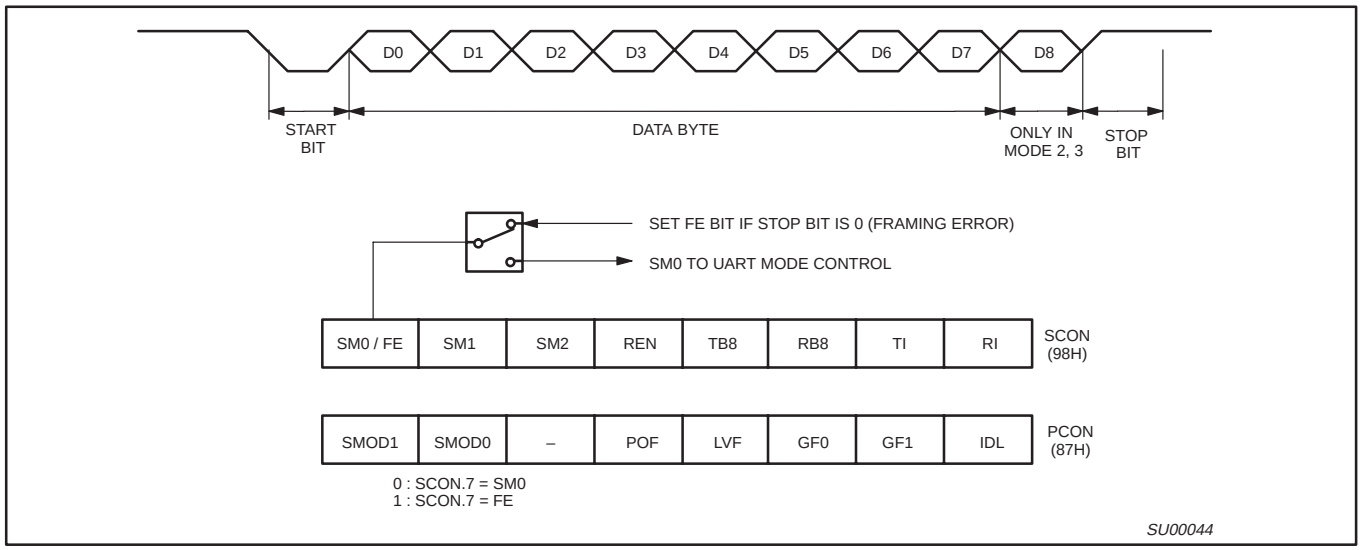


Figure 19. UART Framing Error Detection

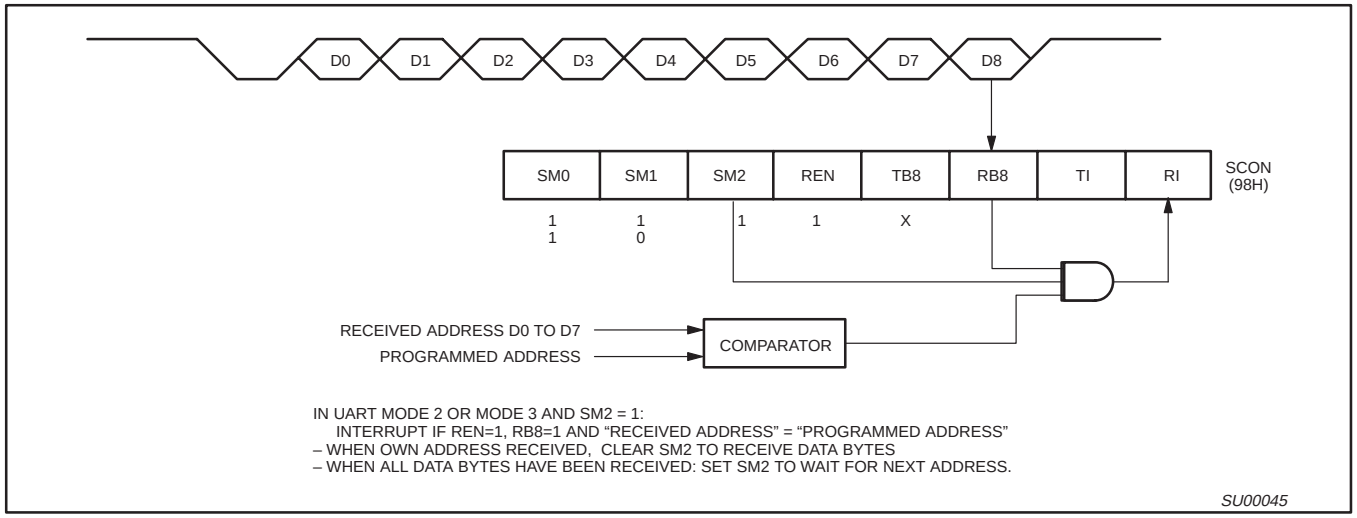


Figure 20. UART Multiprocessor Communication, Automatic Address Recognition

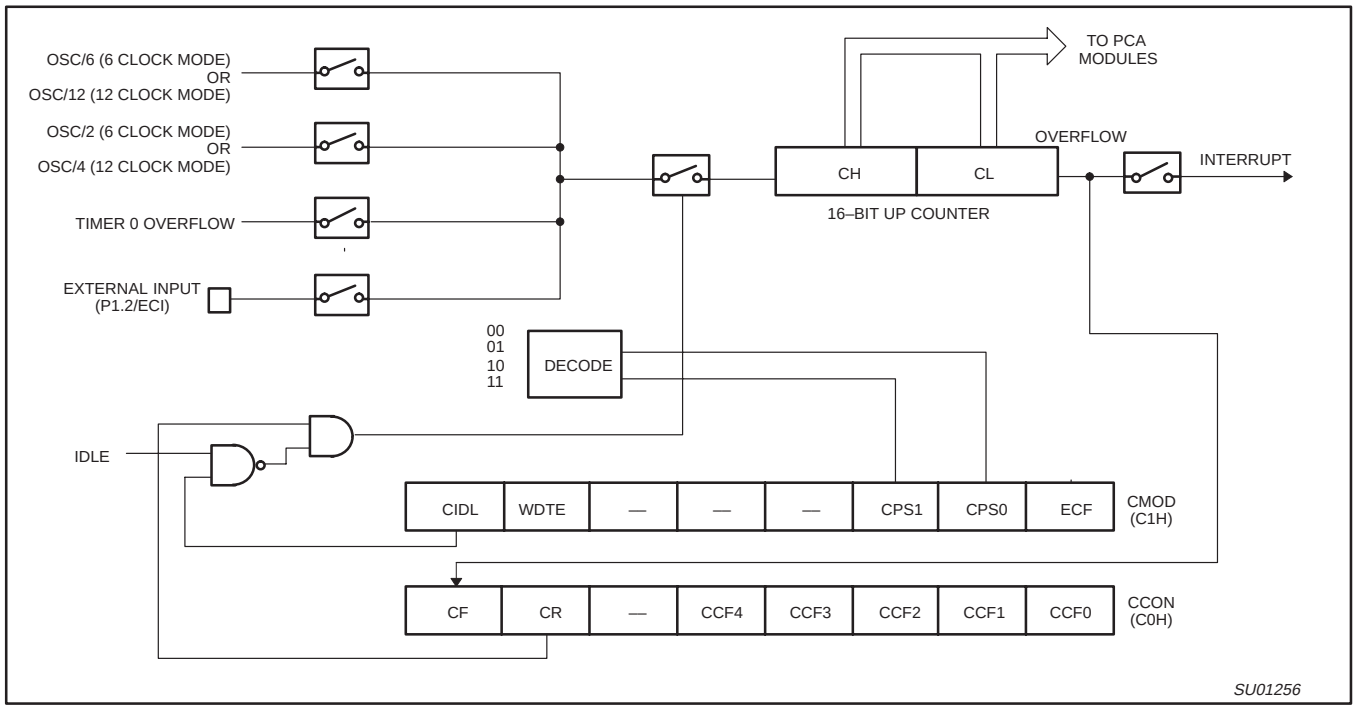


Figure 26. PCA Timer/Counter

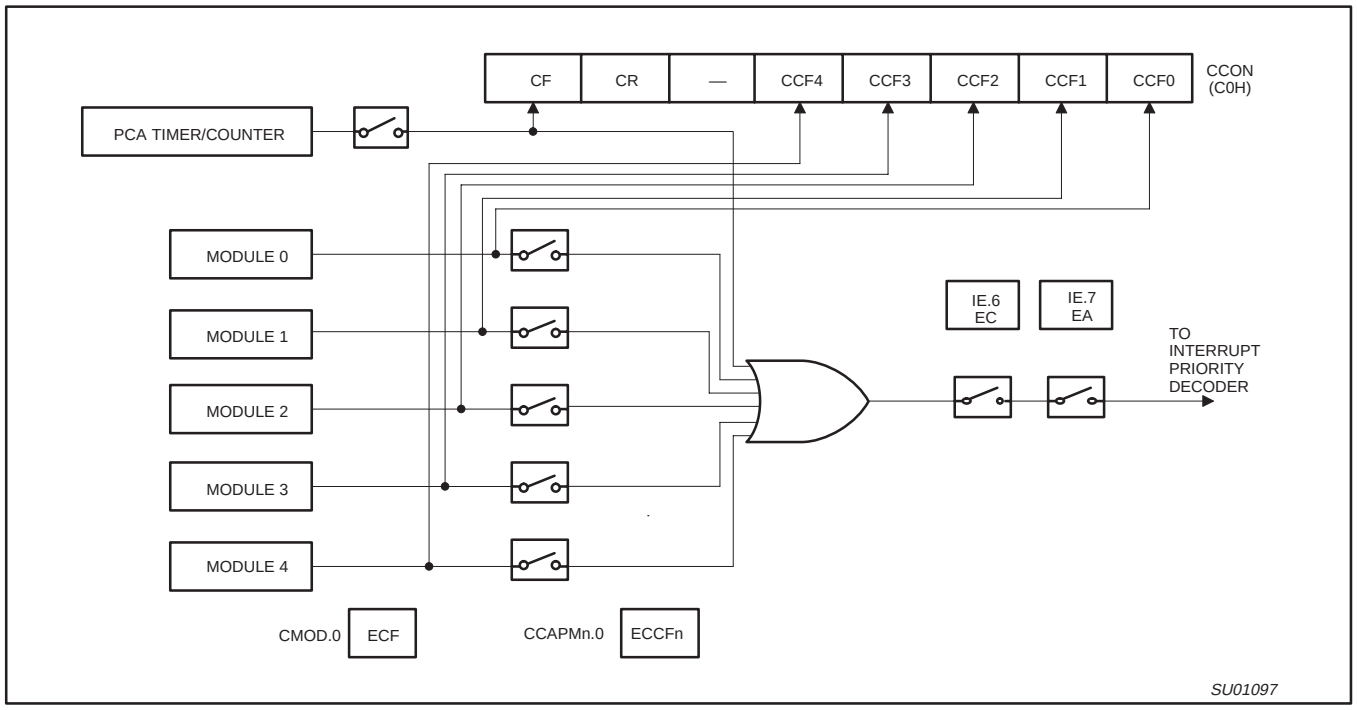


Figure 27. PCA Interrupt System

Expanded Data RAM Addressing

The P89C51RA2/RB2/RC2/RD2xx has internal data memory that is mapped into four separate segments: the lower 128 bytes of RAM, upper 128 bytes of RAM, 128 bytes Special Function Register (SFR), and 256 bytes expanded RAM (ERAM) (768 bytes for the RD2xx).

The four segments are:

1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
4. The 256/768-bytes expanded RAM (ERAM, 00H – 1FFH/2FFH) are indirectly accessed by move external instruction, MOVX, and with the EXTRAM bit cleared, see Figure 38.

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction. Instructions that use direct addressing access SFR space. For example:

MOV 0A0H,#data

accesses the SFR at location 0A0H (which is P2). Instructions that use indirect addressing access the Upper 128 bytes of data RAM.

For example:

MOV @R0,acc

where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).

The ERAM can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory is physically located on-chip, logically occupies the first 256/768 bytes of external data memory in the P89C51RA2/RB2/RC2/89C51RD2.

With EXTRAM = 0, the ERAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. An access to ERAM will not affect ports P0, P3.6 (WR#) and P3.7 (RD#). P2 SFR is output during external addressing. For example, with EXTRAM = 0,

MOVX @R0,acc

where R0 contains 0A0H, accesses the ERAM at address 0A0H rather than external memory. An access to external data memory locations higher than the ERAM will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address bus, and P3.6 and P3.7 as write and read timing signals. Refer to Figure 39.

With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an 8-bit address multiplexed with data on Port 0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a 16-bit address. Port 2 outputs the high-order eight address bits (the contents of DPH) while Port 0 multiplexes the low-order eight address bits (DPL) with data. MOVX @Ri and MOVX @DPTR will generate either read or write signals on P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the ERAM.

AUXR Address = 8EH Reset Value = xxxx xx00B

Not Bit Addressable

	—	—	—	—	—	—	**EXTRAM**	**AO**
Bit:	7	6	5	4	3	2	1	0

Symbol	Function
AO	Disable/Enable ALE
	AO **Operating Mode**
	0 ALE is emitted at a constant rate of $^1/_6$ the oscillator frequency (12-clock mode; $^1/_3$ f_{OSC} in 6-clock mode).
	1 ALE is active only during off-chip memory access.
EXTRAM	Internal/External RAM access using MOVX @Ri/@DPTR
	EXTRAM **Operating Mode**
	0 Internal ERAM access using MOVX @Ri/@DPTR
	1 External data memory access.
—	Not implemented, reserved for future use*.

NOTE:
*User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

SU01613

Figure 38. AUXR: Auxiliary Register

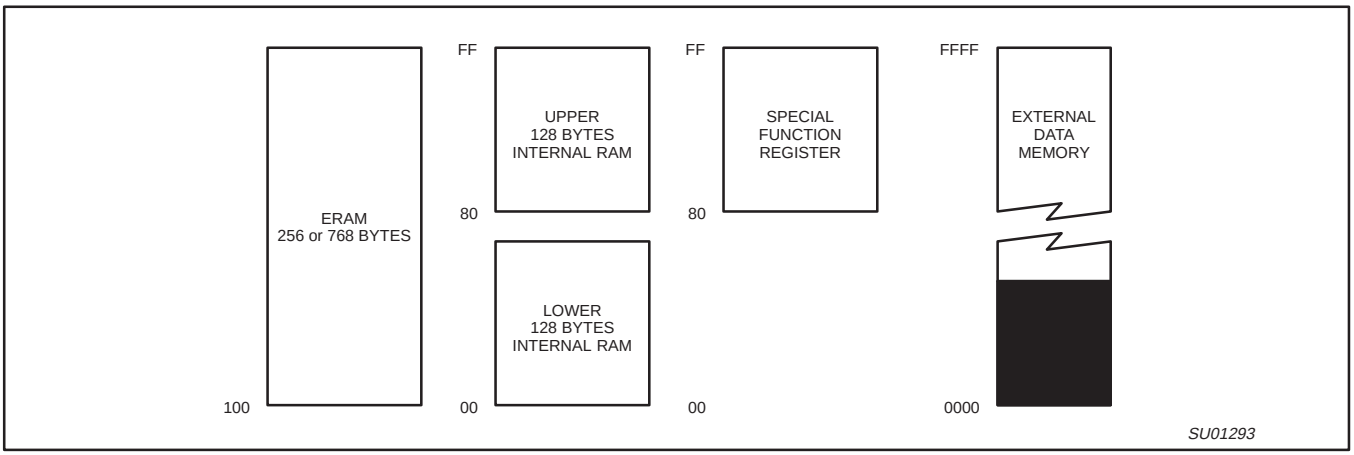


Figure 39. Internal and External Data Memory Address Space with EXTRAM = 0

HARDWARE WATCHDOG TIMER (ONE-TIME ENABLED WITH RESET-OUT FOR P89C51RA2/RB2/RC2/RD2xx)

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upset. The WDT consists of a 14-bit counter and the WatchDog Timer reset (WDTRST) SFR. The WDT is disabled at reset. To enable the WDT, the user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When the WDT is enabled, it will increment every machine cycle while the oscillator is running and there is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When the WDT overflows, it will drive an output reset HIGH pulse at the RST-pin (see the note below).

Using the WDT

To enable the WDT, the user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH) and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT, the user must write 01EH and 0E1H to WDTRST. WDTRST is a write only register. The WDT counter cannot be read or written. When the WDT overflows, it will generate an output RESET pulse at the reset pin (see note below). The RESET pulse duration is $98 \times T_{OSC}$ (6-clock mode; 196 in 12-clock mode), where $T_{OSC} = 1/f_{OSC}$. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

BootROM that is shadowed over a portion of the user code memory space. A user program simply calls the common entry point with appropriate parameters in the BootROM to accomplish the desired operation. BootROM operations include: erase block, program byte, verify byte, program security bit, etc. The BootROM overlays the program memory space at the top of the address space from FC00 to FFFF hex, when it is enabled. The BootROM may be turned off so that the upper 1 kbyte of user program memory is accessible for execution.

Clock Mode

The clock mode feature sets operating frequency to be 1/12 or 1/6 of the oscillator frequency. The clock mode configuration bit, FX2, is located in the Security Block (See Table 8). FX2, when programmed, will override the SFR clock mode bit (X2) in the CKCON register. If FX2 is erased, then the SFR bit (X2) may be used to select between 6-clock and 12-clock mode.

Table 8.

CLOCK MODE CONFIG BIT (FX2)	X2 bit in CKCON	DESCRIPTION
erased	0	12-clock mode (default)
erased	1	6-clock mode
programmed	x	6-clock mode

NOTE:
1. Default clock mode after ChipErase is set to SFR selection.

FLASH MEMORY SPACES
Flash User Code Memory Organization

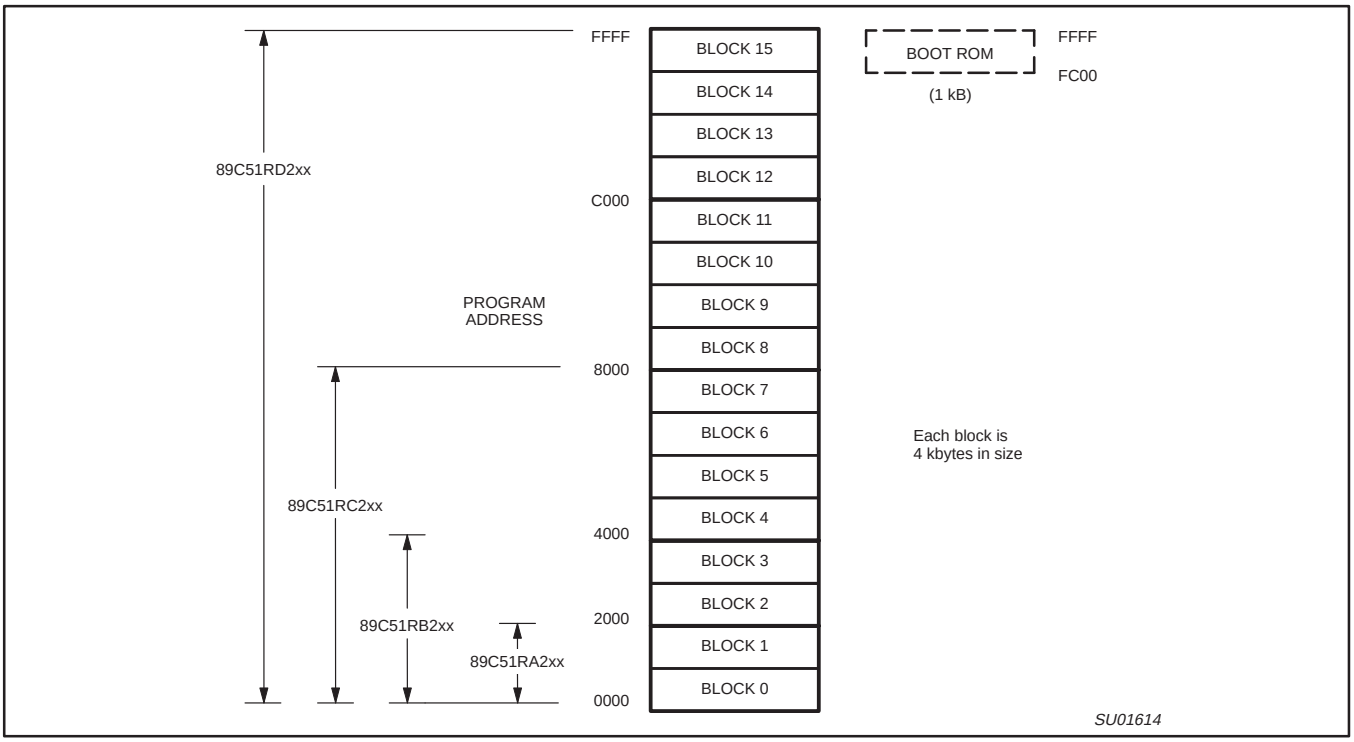


Figure 40. Flash Memory Configurations

Power-On Reset Code Execution

The P89C51RA2/RB2/RC2/RD2xx contains two special Flash registers: the BOOT VECTOR and the STATUS BYTE. At the falling edge of reset, the P89C51RA2/RB2/RC2/RD2xx examines the contents of the Status Byte. If the Status Byte is set to zero, power-up execution starts at location 0000H, which is the normal start address of the user's application code. When the Status Byte is set to a value other than zero, the contents of the Boot Vector is used as the high byte of the execution address and the low byte is set to 00H. The factory default setting is 0FCH, corresponds to the address 0FC00H for the factory masked-ROM ISP boot loader. A custom boot loader can be written with the Boot Vector set to the custom boot loader.

NOTE: When erasing the Status Byte or Boot Vector, both bytes are erased at the same time. It is necessary to reprogram the Boot Vector after erasing and updating the Status Byte.

RECORD TYPE	COMMAND/DATA FUNCTION
03 (Cont.)	Subfunction Code = 07 (Full Chip Erase) Erases all blocks, security bits, and sets status byte and boot vector to default values ff = 07 ss = don't care dd = don't care Example: :0100000307F5 full chip erase Subfunction Code = 0C (Erase 4K Blocks) ff = 0C ss = block code as shown below: Block 0 , 0k~4k , 00H Block 1 , 4k~8k , 10H Block 2 , 8k~12k , 20H (only available on RD2 / RC2 / RB2) Block 3 , 12k~16k , 30H (only available on RD2 / RC2 / RB2) Block 4 , 16k~20k , 40H (only available on RD2 / RC2) Block 5 , 20k~24k , 50H (only available on RD2 / RC2) Block 6 , 24k~28k , 60H (only available on RD2 / RC2) Block 7 , 28k~32k , 70H (only available on RD2 / RC2) Block 8 , 32k~36k , 80H (only available on RD2) Block 9 , 36k~40k , 90H (only available on RD2) Block 10, 40k~44k , A0H (only available on RD2) Block 11, 44k~48k , B0H (only available on RD2) Block 12, 48k~52k , C0H (only available on RD2) Block 13, 52k~56k , D0H (only available on RD2) Block 14, 56k~60k , E0H (only available on RD2) Block 15, 60k~64k , F0H (only available on RD2) Example: :020000030C20CF (Erase 4k block #2)
04	Display Device Data or Blank Check – Record type 04 causes the contents of the entire Flash array to be sent out the serial port in a formatted display. This display consists of an address and the contents of 16 bytes starting with that address. No display of the device contents will occur if security bit 2 has been programmed. Data to the serial port is initiated by the reception of any character and terminated by the reception of any character. General Format of Function 04 :05xxxx04sssseeeeffcc Where: 05 = number of bytes (hex) in record xxxx = required field, but value is a "don't care" 04 = "Display Device Data or Blank Check" function code ssss = starting address eeee = ending address ff = subfunction 00 = display data 01 = blank check 02 = display data in data block (valid addresses: 0001~0FFFH) cc = checksum Example 1: :0500000440004FFF0069 display 4000–4FFF Example 2: :0500000400000FFF02E7 display data in data block (the data at address 0000 is invalid)

Security

The security feature protects against software piracy and prevents the contents of the Flash from being read. The Security Lock bits are located in Flash. The P89C51RA2/RB2/RC2/RD2xx has three programmable security lock bits that will provide different levels of protection for the on-chip code and data (see Table 11).

Table 11.

	SECURITY LOCK BITS[1]			PROTECTION DESCRIPTION
LEVEL	LB1	LB2	LB3	
1	0	0	0	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory.
2	1	0	0	Block erase is disabled. Erase or programming of the status byte or boot vector is disabled.
3	1	1	0	Verify of code memory is disabled.
4	1	1	1	External execution is disabled.

NOTE:
1. Security bits are independent of each other. Full-chip erase may be performed regardless of the state of the security bits.
2. Any other combination of lock bits is undefined.
3. Setting LBx doesn't prevent programming of unprogrammed bits.

ABSOLUTE MAXIMUM RATINGS[1, 2, 3]

PARAMETER	RATING	UNIT
Operating temperature under bias	0 to +70 or –40 to +85	°C
Storage temperature range	–65 to +150	°C
Voltage on $\overline{EA}/V_{PP}$ pin to V_{SS}	0 to +13.0	V
Voltage on any other pin to V_{SS}	–0.5 to +6.5	V
Maximum I_{OL} per I/O pin	15	mA
Power dissipation (based on package heat transfer limitations, not device power consumption)	1.5	W

NOTES:
1. Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the AC and DC Electrical Characteristics section of this specification is not implied.
2. This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maximum.
3. Parameters are valid over operating temperature range unless otherwise specified. All voltages are with respect to V_{SS} unless otherwise noted.

DC ELECTRICAL CHARACTERISTICS

T_{amb} = 0 °C to +70 °C or –40 °C to +85 °C; V_{CC} = 5 V ± 10%; V_{SS} = 0 V

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP[1]	MAX	
V_{IL}	Input low voltage	4.5 V < V_{CC} < 5.5 V	–0.5		$0.2V_{CC}$–0.1	V
V_{IH}	Input high voltage (ports 0, 1, 2, 3, $\overline{EA}$)		$0.2V_{CC}$+0.9		V_{CC}+0.5	V
V_{IH1}	Input high voltage, XTAL1, RST		$0.7V_{CC}$		V_{CC}+0.5	V
V_{OL}	Output low voltage, ports 1, 2, 3[8]	V_{CC} = 4.5 V I_{OL} = 1.6 mA[2]			0.4	V
V_{OL1}	Output low voltage, port 0, ALE, $\overline{PSEN}$ [7, 8]	V_{CC} = 4.5 V I_{OL} = 3.2 mA[2]			0.45	V
V_{OH}	Output high voltage, ports 1, 2, 3 [3]	V_{CC} = 4.5 V I_{OH} = –30 µA	V_{CC} – 0.7			V
V_{OH1}	Output high voltage (port 0 in external bus mode), ALE[9], $\overline{PSEN}$[3]	V_{CC} = 4.5 V I_{OH} = –3.2 mA	V_{CC} – 0.7			V
I_{IL}	Logical 0 input current, ports 1, 2, 3	V_{IN} = 0.4 V	–1		–75	µA
I_{TL}	Logical 1-to-0 transition current, ports 1, 2, 3[6]	V_{IN} = 2.0 V See Note 4			–650	µA
I_{LI}	Input leakage current, port 0	0.45 < V_{IN} < V_{CC} – 0.3			±10	µA
I_{CC}	Power supply current (see Figure 49): Active mode (see Note 5) Idle mode (see Note 5) Power-down mode or clock stopped (see Figure 55 for conditions) Programming and erase mode	See Note 5 T_{amb} = 0 °C to 70 °C T_{amb} = –40 °C to +85 °C f_{osc} = 20 MHz		 < 30 < 40 60	 100 125	 µA µA mA
R_{RST}	Internal reset pull-down resistor		40		225	kΩ
C_{IO}	Pin capacitance[10] (except $\overline{EA}$)				15	pF

NOTES:

1. Typical ratings are not guaranteed. The values listed are at room temperature, 5 V.
2. Capacitive loading on ports 0 and 2 may cause spurious noise to be superimposed on the V_{OL}s of ALE and ports 1 and 3. The noise is due to external bus capacitance discharging into the port 0 and port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE pin may exceed 0.8 V. In such cases, it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input. I_{OL} can exceed these conditions provided that no single output sinks more than 5 mA and no more than two outputs exceed the test conditions.
3. Capacitive loading on ports 0 and 2 may cause the V_{OH} on ALE and $\overline{PSEN}$ to momentarily fall below the V_{CC}–0.7 specification when the address bits are stabilizing.
4. Pins of ports 1, 2 and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2 V.
5. See Figures 52 through 55 for I_{CC} test conditions and Figure 49 for I_{CC} vs Freq.
   Active mode: $I_{CC(MAX)}$ = (10.5 + 0.9 × FREQ.[MHz])mA in 12-clock mode
   Idle mode: $I_{CC(MAX)}$ = (2.5 + 0.33 × FREQ.[MHz])mA in 12-clock mode
6. This value applies to T_{amb} = 0 °C to +70 °C.
7. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
8. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 15 mA (*NOTE: This is 85 °C specification.)
   Maximum I_{OL} per 8-bit port: 26 mA
   Maximum total I_{OL} for all outputs: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
9. ALE is tested to V_{OH1}, except when ALE is off then V_{OH} is the voltage specification.
10. Pin capacitance is characterized but not tested. Pin capacitance is less than 25 pF. Pin capacitance of ceramic package is less than 15 pF (except $\overline{EA}$ is 25 pF).

AC ELECTRICAL CHARACTERISTICS (12-CLOCK MODE)

T_{amb} = 0 °C to +70 °C or –40 °C to +85 °C; V_{CC} = 5 V ± 10%, V_{SS} = 0 V[1, 2, 3]

SYMBOL	FIGURE	PARAMETER	VARIABLE CLOCK[4]		33 MHz CLOCK[4]		UNIT
			MIN	MAX	MIN	MAX	
$1/t_{CLCL}$	42	Oscillator frequency	0	33			MHz
t_{LHLL}	42	ALE pulse width	$2t_{CLCL}$–40		21		ns
t_{AVLL}	42	Address valid to ALE low	t_{CLCL}–25		5		ns
t_{LLAX}	42	Address hold after ALE low	t_{CLCL}–25		5		ns
t_{LLIV}	42	ALE low to valid instruction in		$4t_{CLCL}$–65		55	ns
t_{LLPL}	42	ALE low to $\overline{PSEN}$ low	t_{CLCL}–25		5		ns
t_{PLPH}	42	$\overline{PSEN}$ pulse width	$3t_{CLCL}$–45		45		ns
t_{PLIV}	42	$\overline{PSEN}$ low to valid instruction in		$3t_{CLCL}$–60		30	ns
t_{PXIX}	42	Input instruction hold after $\overline{PSEN}$	0		0		ns
t_{PXIZ}	42	Input instruction float after $\overline{PSEN}$		t_{CLCL}–25		5	ns
t_{AVIV}	42	Address to valid instruction in		$5t_{CLCL}$–80		70	ns
t_{PLAZ}	42	$\overline{PSEN}$ low to address float		10		10	ns
Data Memory							
t_{RLRH}	43, 44	$\overline{RD}$ pulse width	$6t_{CLCL}$–100		82		ns
t_{WLWH}	43, 44	$\overline{WR}$ pulse width	$6t_{CLCL}$–100		82		ns
t_{RLDV}	43, 44	$\overline{RD}$ low to valid data in		$5t_{CLCL}$–90		60	ns
t_{RHDX}	43, 44	Data hold after $\overline{RD}$	0		0		ns
t_{RHDZ}	43, 44	Data float after $\overline{RD}$		$2t_{CLCL}$–28		32	ns
t_{LLDV}	43, 44	ALE low to valid data in		$8t_{CLCL}$–150		90	ns
t_{AVDV}	43, 44	Address to valid data in		$9t_{CLCL}$–165		105	ns
t_{LLWL}	43, 44	ALE low to $\overline{RD}$ or $\overline{WR}$ low	$3t_{CLCL}$–50	$3t_{CLCL}$+50	40	140	ns
t_{AVWL}	43, 44	Address valid to $\overline{WR}$ low or $\overline{RD}$ low	$4t_{CLCL}$–75		45		ns
t_{QVWX}	43, 44	Data valid to $\overline{WR}$ transition	t_{CLCL}–30		0		ns
t_{WHQX}	43, 44	Data hold after $\overline{WR}$	t_{CLCL}–25		5		ns
t_{QVWH}	44	Data valid to $\overline{WR}$ high	$7t_{CLCL}$–130		80		ns
t_{RLAZ}	43, 44	$\overline{RD}$ low to address float		0		0	ns
t_{WHLH}	43, 44	$\overline{RD}$ or $\overline{WR}$ high to ALE high	t_{CLCL}–25	t_{CLCL}+25	5	55	ns
External Clock							
t_{CHCX}	46	High time	17	t_{CLCL}–t_{CLCX}			ns
t_{CLCX}	46	Low time	17	t_{CLCL}–t_{CHCX}			ns
t_{CLCH}	46	Rise time		5			ns
t_{CHCL}	46	Fall time		5			ns
Shift Register							
t_{XLXL}	45	Serial port clock cycle time	$12t_{CLCL}$		360		ns
t_{QVXH}	45	Output data setup to clock rising edge	$10t_{CLCL}$–133		167		ns
t_{XHQX}	45	Output data hold after clock rising edge	$2t_{CLCL}$–80		50		ns
t_{XHDX}	45	Input data hold after clock rising edge	0		0		ns
t_{XHDV}	45	Clock rising edge to input data valid		$10t_{CLCL}$–133		167	ns

NOTES:
1. Parameters are valid over operating temperature range unless otherwise specified.
2. Load capacitance for port 0, ALE, and $\overline{PSEN}$ = 100 pF, load capacitance for all other outputs = 80 pF.
3. Interfacing the microcontroller to devices with float times up to 45 ns is permitted. This limited bus contention will not cause damage to Port 0 drivers.
4. Parts are tested to 3.5 MHz, but guaranteed to operate down to 0 Hz.

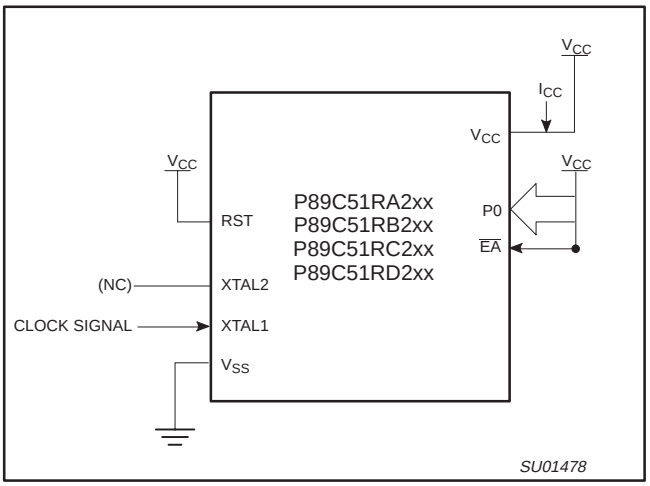


Figure 52. I_{CC} Test Condition, Active Mode, T_{amb} = 25 °C. All other pins are disconnected

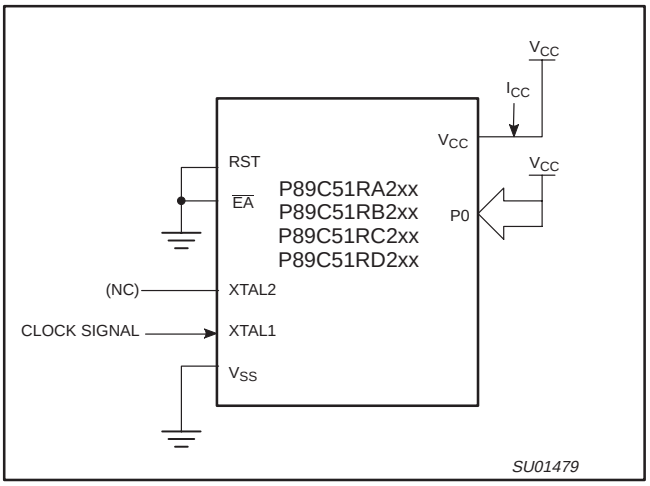


Figure 53. I_{CC} Test Condition, Idle Mode, T_{amb} = 25 °C. All other pins are disconnected

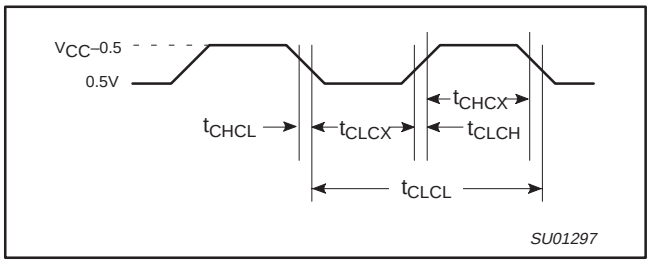


Figure 54. Clock Signal Waveform for I_{CC} Tests in Active and Idle Modes. $t_{CLCL} = t_{CHCL}$ = 10 ns

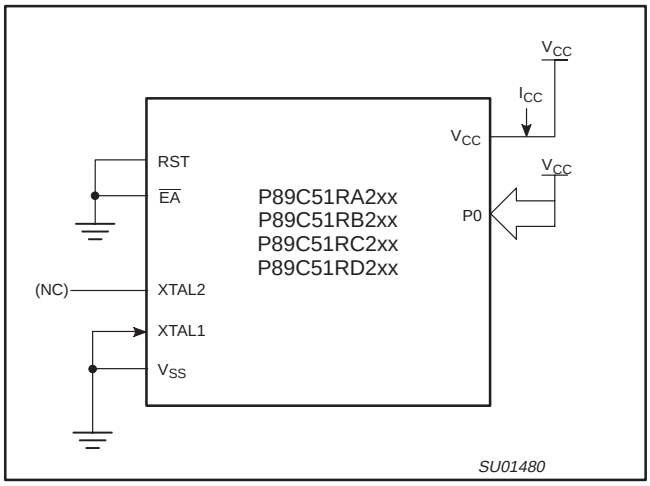
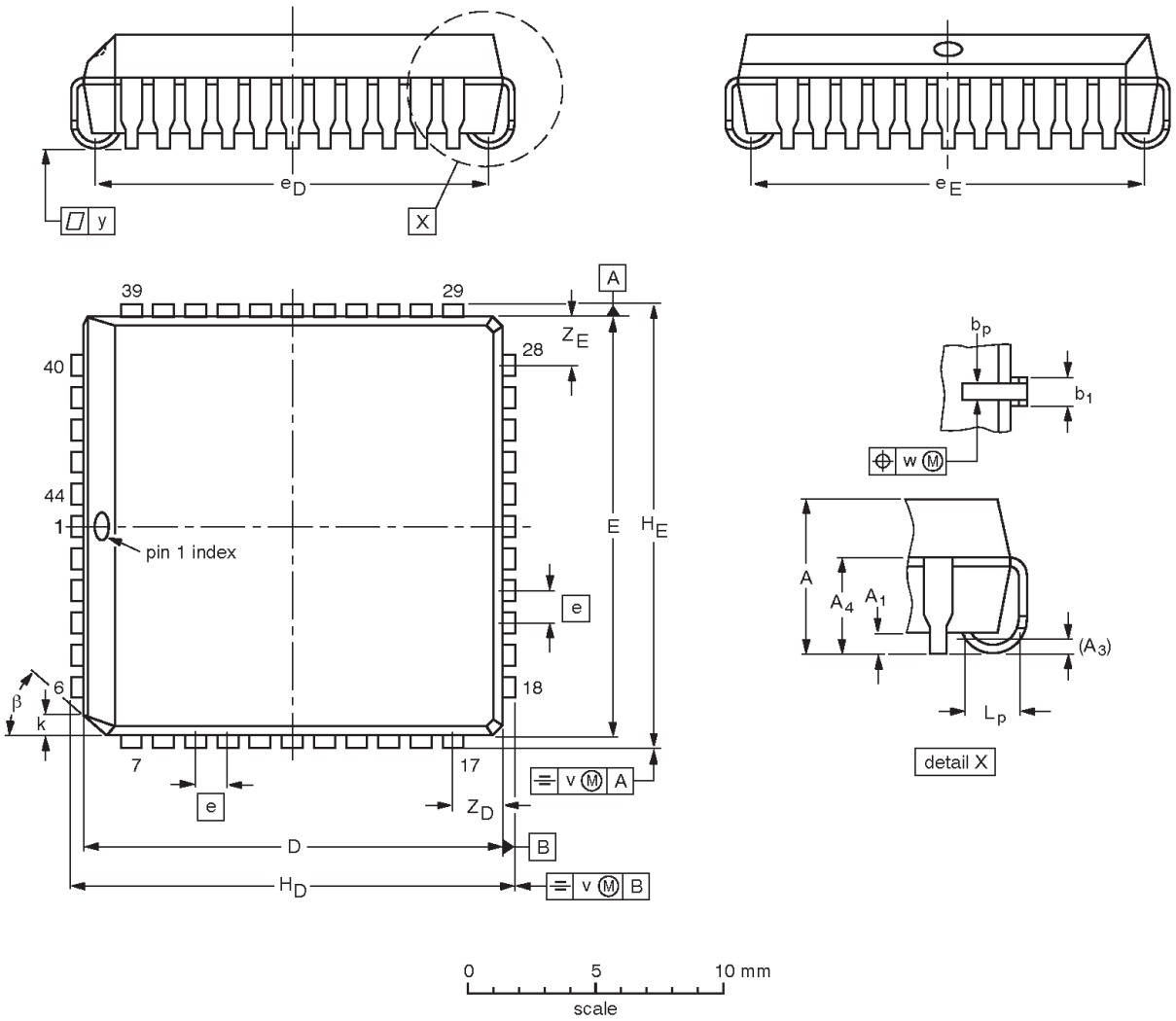


Figure 55. I_{CC} Test Condition, Power Down Mode. All other pins are disconnected; V_{CC} = 2 V to 5.5 V

PLCC44: plastic leaded chip carrier; 44 leads **SOT187-2**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	16.66 16.51	16.66 16.51	1.27	16.00 14.99	16.00 14.99	17.65 17.40	17.65 17.40	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.656 0.650	0.656 0.650	0.05	0.63 0.59	0.63 0.59	0.695 0.685	0.695 0.685	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT187-2	112E10	MS-018	EDR-7319			~~99-12-27~~ 01-11-14